SLLS101D - JULY 1985 - REVISED APRIL 2003

- Bidirectional Transceivers
- Meet or Exceed the Requirements of ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A and ITU Recommendations V.11 and X.27
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- 3-State Driver and Receiver Outputs
- Individual Driver and Receiver Enables
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- Driver Output Capability . . . ±60 mA Max
- Thermal Shutdown Protection
- Driver Positive and Negative Current Limiting
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 50 mV Typ
- Operate From Single 5-V Supply

description/ordering information

The SN65176B and SN75176B differential bus transceivers are integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines and meet ANSI Standards TIA/EIA-422-B and TIA/EIA-485-A and ITU Recommendations V.11 and X.27.

The SN65176B and SN75176B combine a 3-state differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or $V_{CC} = 0$. These ports feature wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications.

ORDERING INFORMATION

TA	PACKAGE [†]		PACKAGET ORDERABLE PART NUMBER	
	PDIP (P)	Tube of 50	SN75176BP	SN75176BP
0°C to 70°C	COIC (D)	Tube of 75	SN75176BD	75176B
0°C to 70°C	SOIC (D)	Reel of 2500	SN75176BDR	75170B
	SOP (PS)	Reel of 2000	SN75176BPSR	A176B
	PDIP (P)	Tube of 50	SN65176BP	SN65176BP
–40°C to 105°C	SOIC (D)	Tube of 75	SN65176BD	65176B
	SOIC (D)	Reel of 2500	SN65176BDR	001700

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description/ordering information (continued)

The driver is designed for up to 60 mA of sink or source current. The driver features positive and negative current limiting and thermal shutdown for protection from line-fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The receiver features a minimum input impedance of 12 k Ω , an input sensitivity of ± 200 mV, and a typical input hysteresis of 50 mV.

The SN65176B and SN75176B can be used in transmission-line applications employing the SN75172 and SN75174 quadruple differential line drivers and SN75173 and SN75175 quadruple differential line receivers.

Function Tables

DRIVER

INPUT	ENABLE	OUTPUTS			
D	DE	Α	В		
Н	Н	Н	L		
L	Н	L	Н		
Х	L	Z	Z		

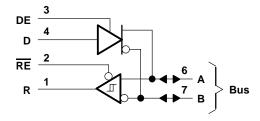
RECEIVER

DIFFERENTIAL INPUTS A-B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
-0.2 V < V _{ID} < 0.2 V	L	?
V _{ID} ≤ -0.2 V	L	L
X	Н	Z
Open	L	?

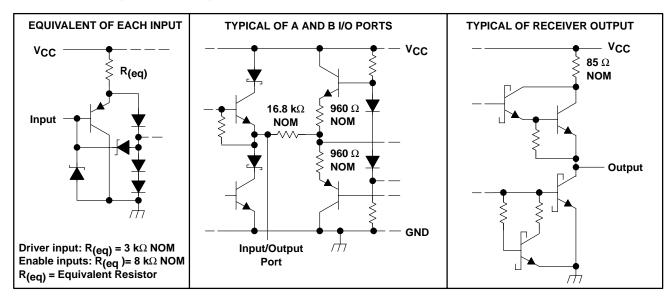
H = high level, L = low level, ? = indeterminate,

X = irrelevant, Z = high impedance (off)

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Enable input voltage, V ₁	
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package	
P package .	85°C/W
PS package	95°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input/output bus voltage, are with respect to network ground terminal.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

SN65176B, SN75176B DIFFERENTIAL BUS TRANSCEIVERS

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recommended operating conditions

			MIN	TYP	MAX	UNIT
Vcc	Supply voltage		4.75	5	5.25	V
\/, or \/, o	V _I or V _{IC} Voltage at any bus terminal (separately or common mode)				12	V
ALOI AIC					-7	٧
V _{IH}	High-level input voltage	D, DE, and RE	2			V
V_{IL}	Low-level input voltage	D, DE, and RE			0.8	V
V _{ID} Differential input voltage (see Note 4)					±12	V
lou	High lovel output ourrest	Driver			-60	mA
ЮН	High-level output current	Receiver			-400	μΑ
la.	Low lovel output ourrent	Driver			60	A
IOL	Low-level output current	Receiver			8	mA
т.	Operating free air temperature	SN65176B	-40		105	°C
T _A	Operating free-air temperature	SN75176B	0		70	C

NOTE 4: Differential input/output bus voltage is measured at the noninverting terminal A, with respect to the inverting terminal B.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONI	MIN	TYP‡	MAX	UNIT	
٧ıĸ	Input clamp voltage	I _I = -18 mA				-1.5	V
٧o	Output voltage	IO = 0		0		6	V
V _{OD1}	Differential output voltage	I _O = 0		1.5	3.6	6	V
IV _{OD2} I	Differential output voltage	R _L = 100 Ω,	See Figure 1	1/2 V _{OD1} or 2¶			V
		$R_L = 54 \Omega$,	See Figure 1	1.5	2.5	5	
V _{OD3}	Differential output voltage	See Note 5		1.5		5	V
ΔIV _{OD} I	Change in magnitude of differential output voltage§	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			±0.2	٧
Voc	Common-mode output voltage	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			+3 –1	٧
ΔΙVOCΙ	Change in magnitude of common-modeoutput voltage§	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			±0.2	V
l _a	Output current	Output disabled,	V _O = 12 V			1	mA
Ю	Output current	See Note 6	V _O = -7 V			-0.8	IIIA
lіН	High-level input current	V _I = 2.4 V				20	μΑ
I _I L	Low-level input current	V _I = 0.4 V				-400	μΑ
		V _O = -7 V				-250	
	Short-circuit output current	V _O = 0				-150	mA
los	Short-circuit output current	$V_O = V_{CC}$				250	ША
		V _O = 12 V				250	
loo	Supply current (total package)	No load	Outputs enabled		42	70	mA
Icc	Supply surrent (total package)	Outputs disabled			26	35	шА

[†] The power-off measurement in ANSI Standard TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs. ‡ All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

NOTES: 5. See ANSI Standard TIA/EIA-485-A, Figure 3.5, Test Termination Measurement 2.

switching characteristics, V_{CC} = 5 V, R_L = 110 Ω , T_A = 25°C (unless otherwise noted)

PARAMETER		TEST	TEST CONDITIONS		TYP	MAX	UNIT
td(OD)	Differential-output delay time	$R_L = 54 \Omega$,	See Figure 3		15	22	ns
t _t (OD)	Differential-output transition time	$R_L = 54 \Omega$,	See Figure 3		20	30	ns
^t PZH	Output enable time to high level	See Figure 4			85	120	ns
t _{PZL}	Output enable time to low level	See Figure 5			40	60	ns
^t PHZ	Output disable time from high level	See Figure 4			150	250	ns
tPLZ	Output disable time from low level	See Figure 5			20	30	ns

^{§ ∆|}V_{OD}| and ∆|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.

 $[\]P$ The minimum $V_{\mbox{OD2}}$ with a 100- Ω load is either 1/2 $V_{\mbox{OD1}}$ or 2 V, whichever is greater.

^{6.} This applies for both power on and off; refer to ANSI Standard TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

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SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
Vo	V_{oa}, V_{ob}	V_{oa}, V_{ob}
VOD1	Vo	V _O
V _{OD2}	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
IVOD3I		V _t (test termination measurement 2)
Δ V _{OD}	$ V_t - \overline{V}_t $	$ V_t - \overline{V}_t $
Voc	V _{os}	V _{os}
∆ VOC	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	$ I_{sa} , I_{sb} $	
lo	$ I_{xa} , I_{xb} $	I _{ia} , I _{ib}

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST C	TEST CONDITIONS			MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	V _O = 2.7 V,	$I_{O} = -0.4 \text{ mA}$			0.2	V
V_{IT-}	Negative-going input threshold voltage	$V_{O} = 0.5 V$,	I _O = 8 mA	-0.2‡			V
V_{hys}	Input hysteresis voltage (V _{IT+} – V _{IT-})				50		mV
٧ıK	Enable Input clamp voltage	I _I = -18 mA				-1.5	V
Vон	High-level output voltage	V _{ID} = 200 mV, See Figure 2	$I_{OH} = -400 \mu A,$	2.7			٧
VOL	Low-level output voltage	V _{ID} = -200 mV, See Figure 2	I _{OL} = 8 mA,			0.45	٧
loz	High-impedance-state output current	V _O = 0.4 V to 2.4 V				±20	μΑ
	Line input current	Other input = 0 V,	V _I = 12 V			1	mA
11	Line input current	See Note 7	V _I = −7 V			-0.8	IIIA
lн	High-level enable input current	V _{IH} = 2.7 V				20	μΑ
I _Ι L	Low-level enable input current	V _{IL} = 0.4 V				-100	μΑ
r _l	Input resistance	V _I = 12 V		12			kΩ
los	Short-circuit output current			-15		-85	mA
loo	Supply gurrant (total page ga)	No load	Outputs enabled		42	55	mA
ICC	Supply current (total package)	INU IUAU	Outputs disabled		26	35	IIIA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 7: This applies for both power on and power off. Refer to EIA Standard TIA/EIA-485-A for exact conditions.

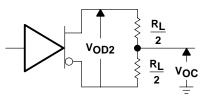


[‡] The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	V _{ID} = 0 to 3 V, See Figure 6		21	35	ns
tPHL	Propagation delay time, high- to low-level output	VID = 0 10 3 V, See Figure 6		23	35	115
^t PZH	Output enable time to high level	See Figure 7		10	20	ns
tPZL	Output enable time to low level	See Figure 7		12	20	115
^t PHZ	Output disable time from high level	See Figure 7		20	35	20
tPLZ	Output disable time from low level	See Figure /		17	25	ns

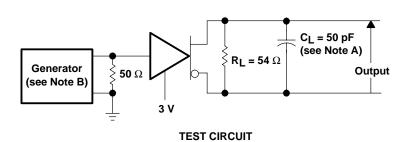
PARAMETER MEASUREMENT INFORMATION

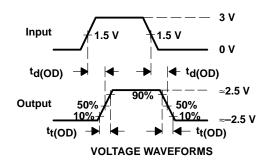


 $\begin{array}{c|c}
R_L & V_{OC} \\
& \downarrow \\
\end{array}$

Figure 1. Driver V_{OD} and V_{OC}

Figure 2. Receiver VOH and VOL



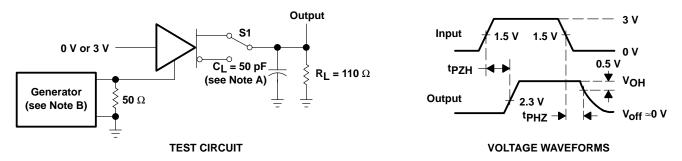


NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \ \Omega$.

Figure 3. Driver Test Circuit and Voltage Waveforms

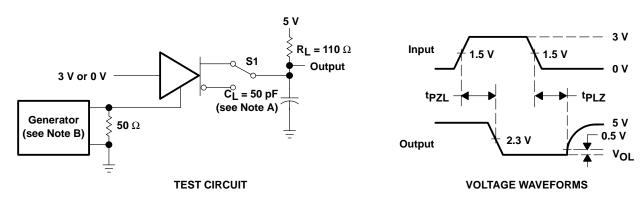
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \ \Omega$.

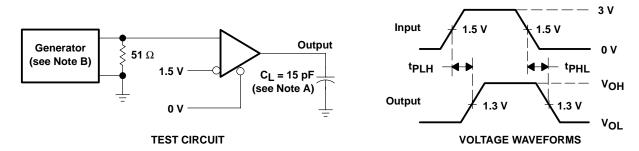
Figure 4. Driver Test Circuit and Voltage Waveforms



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.

Figure 5. Driver Test Circuit and Voltage Waveforms



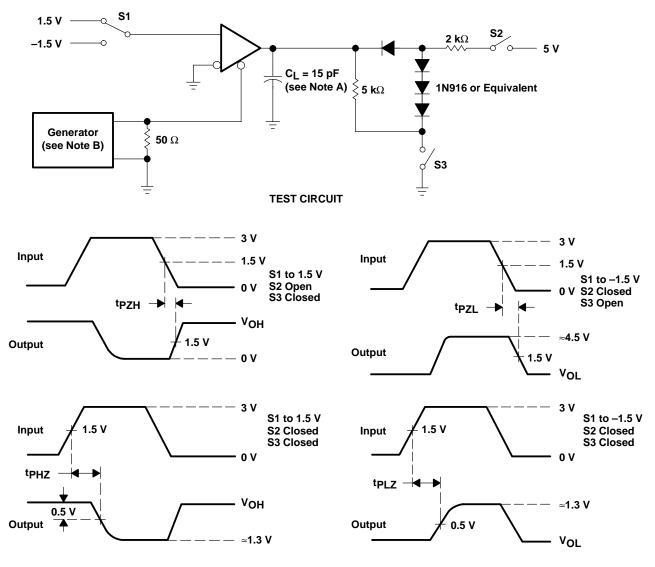
NOTES: A. CL includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 8 ns

Figure 6. Receiver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



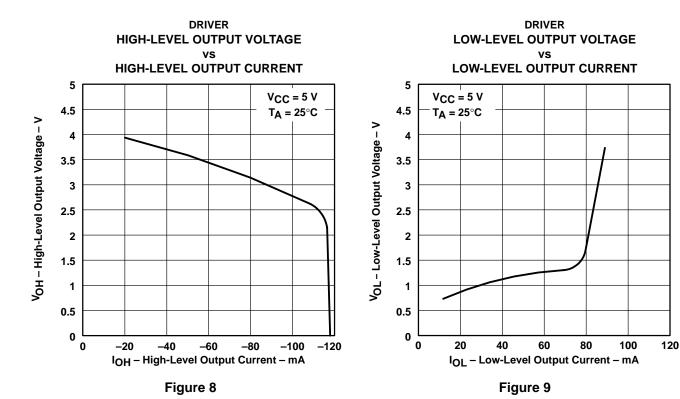
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.

Figure 7. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS



DRIVER DIFFERENTIAL OUTPUT VOLTAGE vs

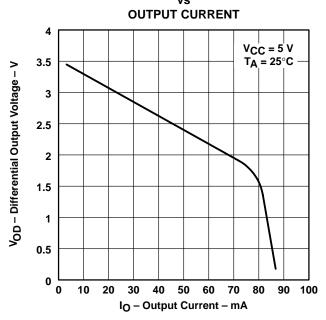


Figure 10

TYPICAL CHARACTERISTICS

RECEIVER HIGH-LEVEL OUTPUT VOLTAGE HIGH-LEVEL OUTPUT CURRENT 5 $V_{1D} = 0.2 V$ T_A = 25°C 4.5 VoH - High-Level Output Voltage - V 4 3.5 3 2.5 $V_{CC} = 5.25 \text{ V}$ 2 **V_{CC}** = 5 **V** 1.5 V_{CC} = 4.75 V 1 0.5 0 -10 -15 -20 -25 -30 -35 -40 -45 -50 IOH - High-Level Output Current - mA

Figure 11

RECEIVER

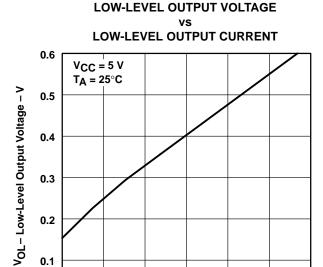


Figure 13

15

IOL - Low-Level Output Current - mA

20

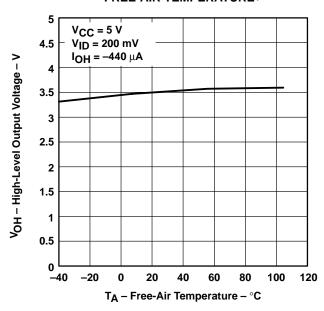
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0

0

5

RECEIVER HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE†



[†]Only the 0°C to 70°C portion of the curve applies to the SN75176B.

Figure 12

RECEIVER LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

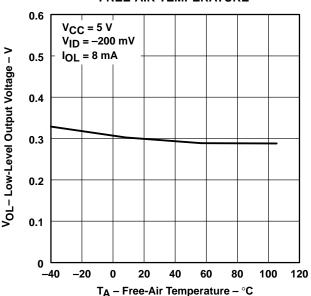
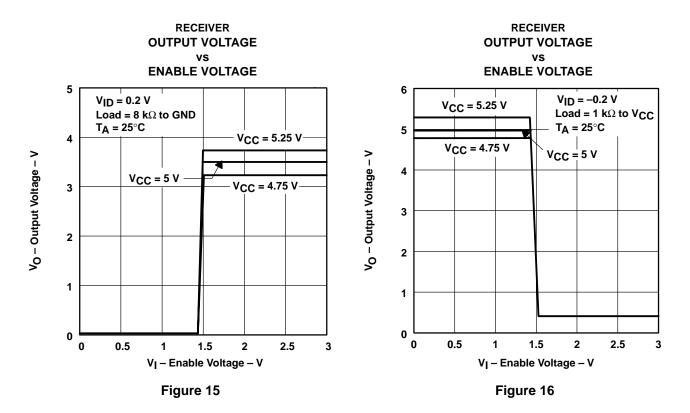


Figure 14

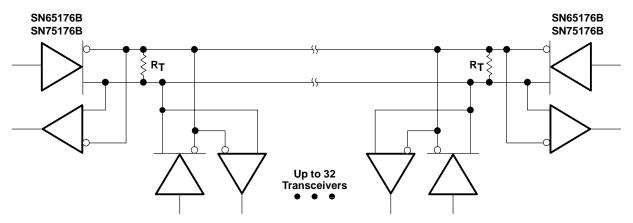
25

30

TYPICAL CHARACTERISTICS



APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance (R_T = Z_O). Stub lengths off the main line should be kept as short as possible.

Figure 17. Typical Application Circuit









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65176BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65176BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65176BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75176BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75176BPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

24-Oct-2006

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

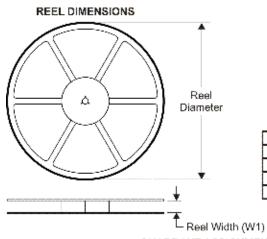
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

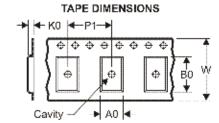
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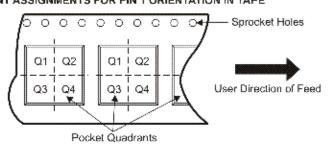
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75176BPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1



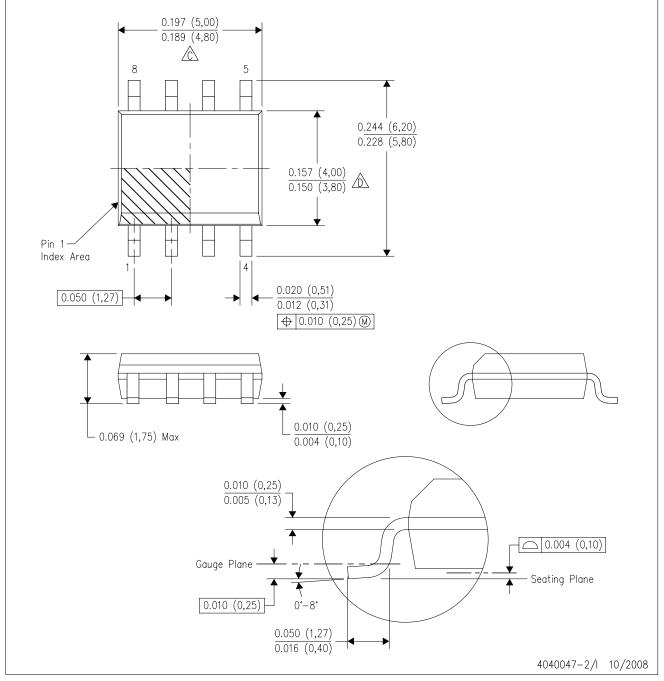


*All dimensions are nominal

7 til dirilonolono aro nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65176BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75176BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75176BPSR	SO	PS	8	2000	346.0	346.0	33.0

D (R-PDSO-G8)

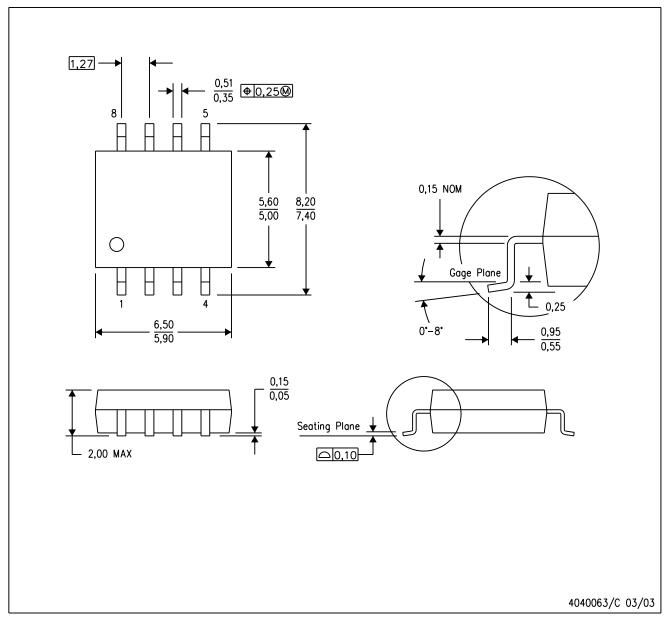
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

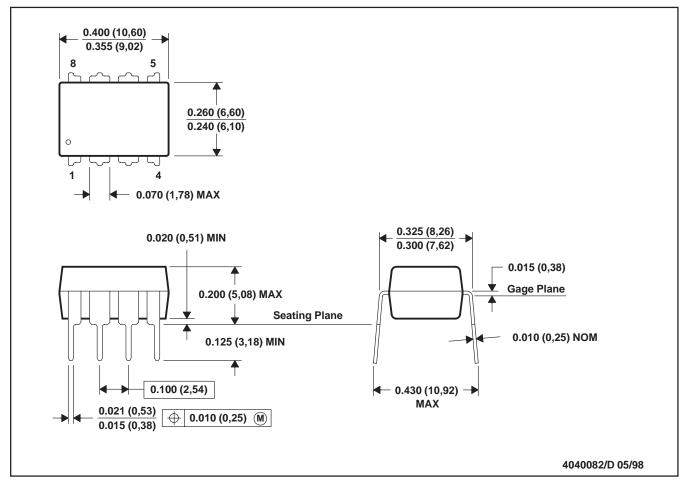
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

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